

Title (en)
QUASICRYSTALLINE COMPOUND AND THE USE THEREOF AS A HEAT INSULATING LAYER

Title (de)
QUASIKRISTALLINE VERBINDUNG UND DEREN VERWENDUNG ALS WÄRMEDÄMMSCHICHT

Title (fr)
COMPOSÉ QUASICRISTALLIN ET SON UTILISATION COMME COUCHE D'ISOLATION THERMIQUE

Publication
EP 1996795 A2 20081203 (DE)

Application
EP 07727208 A 20070322

Priority
• EP 2007052732 W 20070322
• EP 06006053 A 20060323
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Abstract (en)
[origin: EP1837484A2] Compounds of formula: Al wCo xM yare new. M is Ni and/or Cr and at least 30 mass% of the compound has a quasi-crystalline structure. W = 70 - 76 and w + x + y = 100. Independent claims are included for: (A) coatings made from or containing the compounds; (B) coating systems containing a coating made from the compounds; (C) multi-layer coating systems containing two or more of the coating systems; (D) use of the compounds as heat-insulating coatings for components subjected to high temperature, especially turbine steam inlets (333) and blades (357); and (E) use of compounds containing aluminum and manganese, at least 30 mass% of the compound having a quasi-crystalline structure, for the same purpose.

IPC 8 full level
F01D 5/28 (2006.01); **C22C 21/00** (2006.01); **C23C 4/08** (2006.01); **C23C 28/00** (2006.01); **C23C 28/02** (2006.01); **C23C 30/00** (2006.01)

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C22C 21/00 (2013.01 - EP US); **C23C 4/08** (2013.01 - EP US); **C23C 28/321** (2013.01 - EP US); **C23C 28/3215** (2013.01 - EP US); **C23C 28/3455** (2013.01 - EP US); **C23C 30/00** (2013.01 - EP US); **F01D 5/288** (2013.01 - EP US); **F05C 2201/0466** (2013.01 - EP US); **F05D 2300/132** (2013.01 - EP US); **Y10T 428/12535** (2015.01 - EP US); **Y10T 428/31678** (2015.04 - EP US)

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